

AMENDMENTS TO THE CLAIMS

The following is a complete, marked up listing of revised claims with a status identifier in parentheses, underlined text indicating insertions, and strikethrough and/or double-bracketed text indicating deletions.

LISTING OF CLAIMS

1. (ORIGINAL) A film carrier tape comprising:
a base film, the base film formed of a first material and including a main area on which a wiring pattern is formed and a peripheral area; and
a reinforcement film formed of an insulating second material, the reinforcement film being provided on the peripheral area of the base film; wherein
a plurality of sprocket holes formed through the reinforcement film and the peripheral area of the base film.
2. (ORIGINAL) A film carrier tape according to claim 1, wherein:
the base film has a upper surface and a lower surface, and further wherein
the wiring pattern is formed in the main area on the upper surface of the base film,
and
the reinforcement film is attached to the lower surface of the base film.
3. (ORIGINAL) A film carrier tape according to claim 1, wherein:
the reinforcement film is formed from a synthetic resin.
4. (CURRENTLY AMENDED) A film carrier tape according to claim ~~1~~3, wherein:

the synthetic resin includes at least one substance selected from a group consisting of polyethylene terephthalate, liquid crystalline polymer, polytetrafluoroethylene, polypropylene, polyethylene, polyamide-66 and polycarbonate.

5. (ORIGINAL) A film carrier tape according to claim 4, wherein:
the synthetic resin includes a major portion of polyethylene terephthalate.
6. (ORIGINAL) A film carrier tape according to claim 1, wherein:
the reinforcement film has a thickness of 20-80 μm .
7. (ORIGINAL) A film carrier tape according to claim 6, wherein:
the base film has a thickness of 25-50 μm .
8. (WITHDRAWN) A method of manufacturing a film carrier tape comprising:
attaching a raw film to a base film, the base film including a main area and a peripheral area;
forming a plurality of sprocket holes through the peripheral area of the base film and the raw film;
forming a wiring pattern on the main area of the base film;
cutting the raw film along a boundary between the main area and the peripheral area of the base film; and
removing a central portion of the raw film corresponding to the main area of the base film, whereby a remaining portion of the raw film reinforces the peripheral area of the base film.
9. (WITHDRAWN) A method of manufacturing a film carrier tape according to claim 8, wherein:
the raw film is attached to a lower surface of the base film and
the wiring pattern is formed on an upper surface of the base film.

10. (WITHDRAWN) A method of manufacturing a film carrier tape according to claim 8, wherein:

wherein the raw film includes a synthetic resin.

11. (WITHDRAWN) A method of manufacturing a film carrier tape according to claim 8; wherein:

the synthetic resin includes at least one substance selected from a group consisting of polyethylene terephthalate, liquid crystalline polymer, polytetrafluoroethylene, polypropylene, polyethylene, polyamide-66 and polycarbonate.

12. (WITHDRAWN) A method of manufacturing a film carrier tape according to claim 8, wherein:

the synthetic resin includes a major portion of polyethylene terephthalate.

13. (WITHDRAWN) A method of manufacturing a film carrier tape according to claim 8, wherein:

the wiring pattern is formed on the main area of the base film before the raw film is cut along the boundary between the main area and the peripheral area of the base film.

14. (WITHDRAWN) A method of manufacturing a film carrier tape according to claim 8, wherein:

the wiring pattern is formed on the main area of the base film after the raw film is cut along the boundary between the main area and the peripheral area of the base film.

15. (WITHDRAWN) A method of manufacturing film carrier tapes comprising:

attaching a raw film to a base film, the base film having a plurality of main areas and a plurality of peripheral areas bounding the main areas;

forming a plurality of sprocket holes through the peripheral areas of the base film and the raw film;

forming a plurality of cuts through the raw film along a plurality of boundaries between the main areas and the peripheral areas of the base film;

forming a plurality of wiring patterns on the main areas of the base film;

removing portions of the raw film from the main areas of the base film, whereby remaining portions of the raw film reinforce the peripheral areas of the base film;

and

separating the base film along the peripheral areas to form a plurality of film carrier tapes.

16. (WITHDRAWN) A method of manufacturing film carrier tapes according to claim 15, wherein:

attaching the raw film to the base film includes forming an adhesive layer between a surface of the raw film and an opposing surface of the base film.

17. (WITHDRAWN) A method of manufacturing a film carrier tape according to claim 15, comprising:

attaching a raw film to the base film;

forming a plurality of sprocket holes through the peripheral area of the base film and the raw film;

forming the wiring pattern on the main area of the base film;

cutting the raw film along a boundary between the main area and the peripheral area of the base film; and

removing a central portion of the raw film corresponding to the main area of the base film, whereby a remaining portion of the raw film form the reinforcement film.

18. (NEW) A film carrier tape comprising:

a base film, the base film formed of a first material and including a main area on which a wiring pattern is formed and a peripheral area; and

a reinforcement film formed of an insulating second material, the reinforcement film being provided on only the peripheral area of the base film; wherein

a plurality of sprocket holes formed through the reinforcement film and the peripheral area of the base film.

19. (NEW) A film carrier tape according to claim 18, wherein:

the base film is formed from an insulating first material, has a main region and a peripheral region at least partially surrounding the main region, and has an upper surface and a lower surface;

the wiring pattern is formed on the upper surface of the base film in the main region; and

the reinforcement film remains only on the lower surface of the base film in the peripheral region.

20. (NEW) A film carrier tape according to claim 19, wherein:

a solder resist layer is provided on the wiring pattern.

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